

COPPER-NICKEL ALLOY ELECTROPLATING APPARATUS

Abstract

Provided is a copper-nickel alloy electroplating
5 apparatus which is capable of stably forming a copper-nickel
plated coating on a workpiece with a uniform composition and
which enables a plating bath to be used for a long period. The
present invention provides a copper-nickel alloy
electroplating apparatus (1), comprising: a cathode chamber (4)
10 in which a workpiece (5) is to be placed; an anode chamber (6);
an anode (7) placed in the anode chamber; an electrically
conductive diaphragm (14) placed to separate the cathode
chamber and the anode chamber from each other; a cathode chamber
oxidation-reduction potential adjusting tank (8) for adjusting
15 the oxidation-reduction potential of a plating liquid in the
cathode chamber; an anode chamber oxidation-reduction
potential adjusting tank (10) for adjusting the
oxidation-reduction potential of a plating liquid in the anode
chamber; and a power supply unit (36) that provides an electric
20 current to flow between the workpiece and the anode.

[FIG. 1]